

ABSTRACT

The imaging apparatus 1 comprises: a semiconductor imaging device 5 which converts incident light to an electrical signal; an optical filter 4 which is opposed to an incident
5 surface of the semiconductor imaging device 5 and transmits light of a certain wavelength; and a three-dimensional substrate 2 fixing the optical filter 4 by means of adhesion using a filler-containing adhesive 6; wherein the diameter of the filler is smaller than or equal to the
10 pixel size of the semiconductor imaging device 5. Degradation of image quality of the imaging apparatus 1 caused by the dropped filler can thus be reduced.